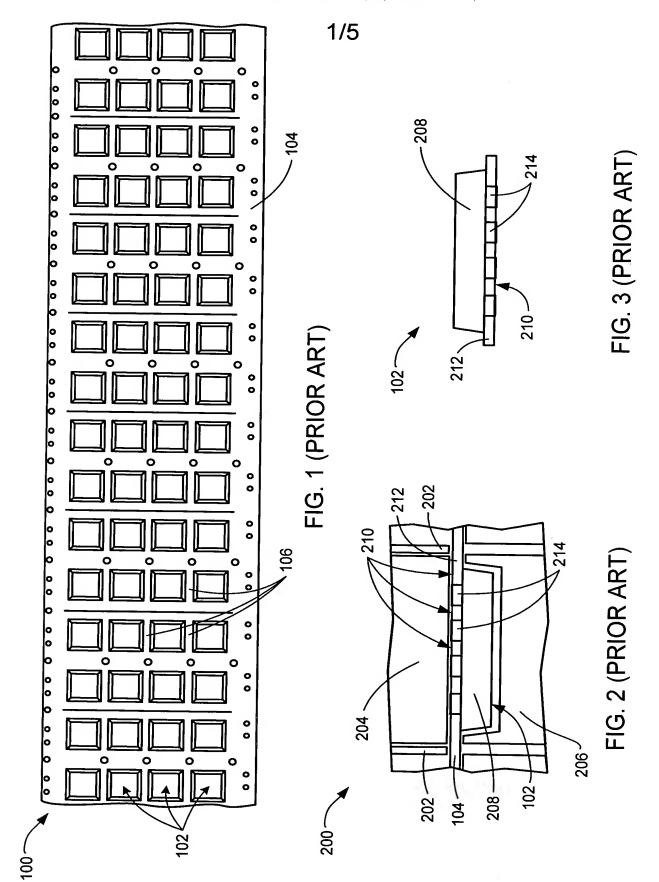
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Title: METHOD FOR FABRICATING
SEMICONDUCTOR PACKAGES, AND LEADFRAME
ASSEMBLIES FOR THE FABRICATION THEREOF
Inventors: Byung Joon Han and Byung Hoon Ahn.

Docket No.: 27-021

Contact: Mikio Ishimaru (408) 738-0592

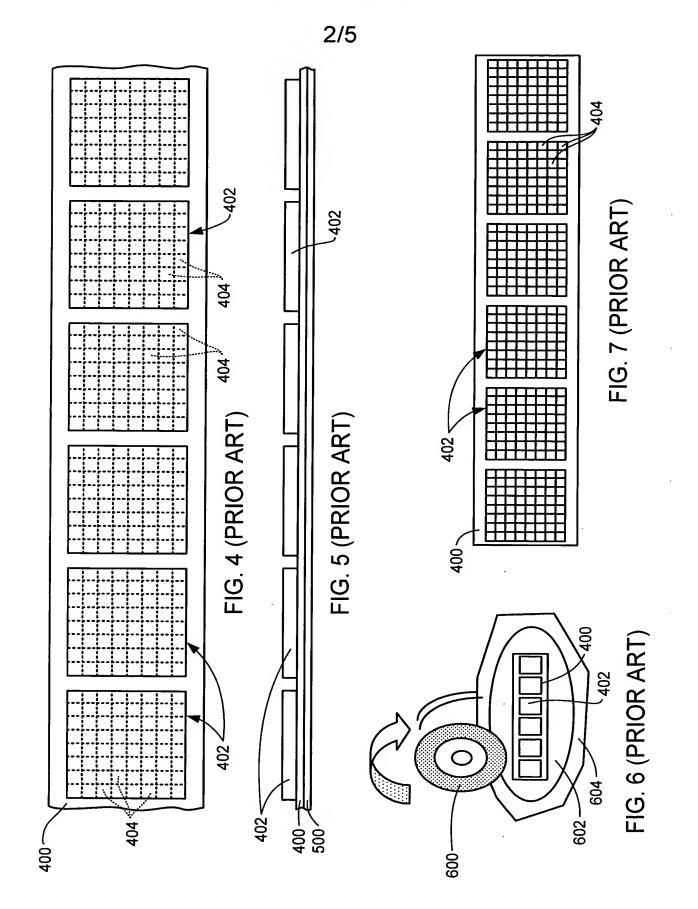


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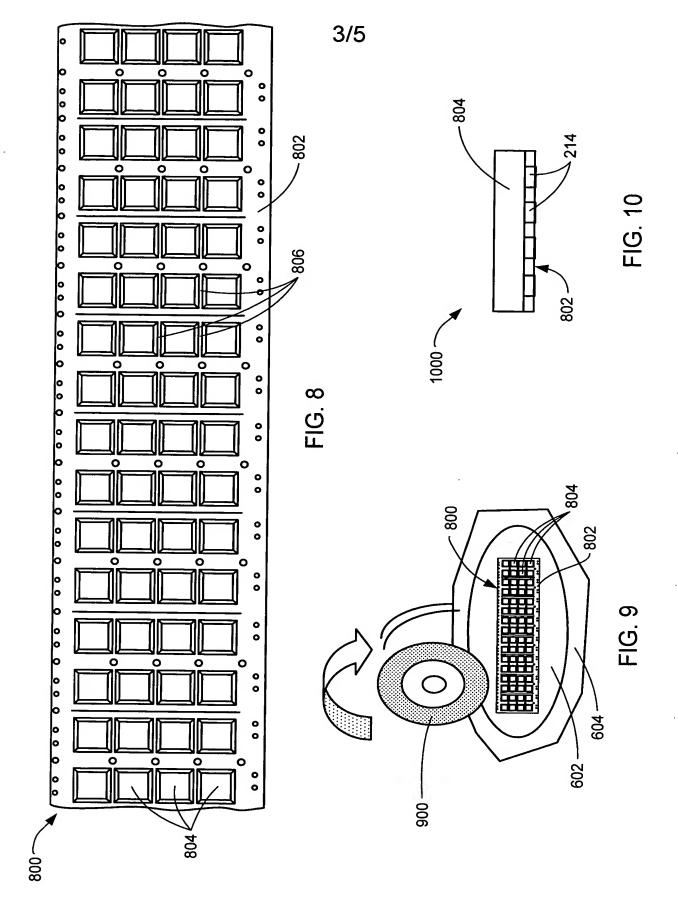


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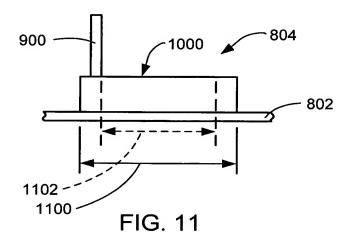
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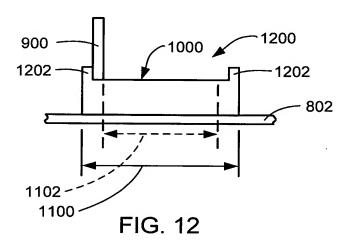
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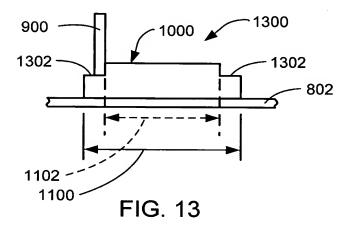


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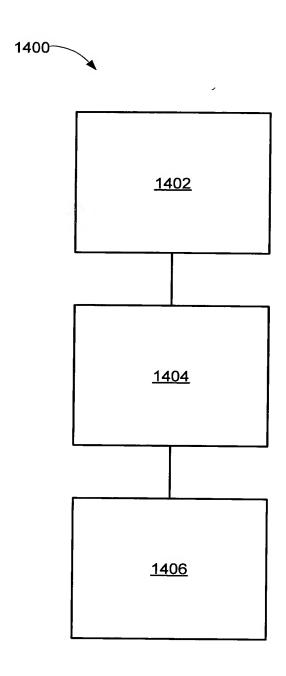


FIG. 14